

ALICE upgrade plans



ALICE Program

- Baseline Program:
 - initial Pb-Pb run in 2010 (1/20th design *L*, i.e. ~ 5 x 10^{25})
 - 2-3 Pb-Pb runs (medium -> design Lum. $L \sim 10^{27}$, 2.75 TeV -> 5.5 TeV) integrate ~ 1nb⁻¹ at least at the higher energy
 - 1-2 p A runs (measure cold nuclear matter effects, e.g. shadowing)
 - 1 low mass ion run (energy density & volume dependence) typ. ArAr
 - continuous running with pp (comp. data, genuine pp physics)
- -> Baseline Program fills "HI runs" to ~ 2019
- Following:
 - program and priorities to be decided based on results
 - Increase int. Luminosity by an order of magnitude (to ~ 10nb⁻¹)
 - Address rare probes (statistics limited: example with 1nb⁻¹ :J/Y: excellent, Y': marginal, Y: ok (14000), Y': low (4000), Y'': very low (2000))
 - lower energies (energy dependence, thresholds, RHIC, pp at 5.5 TeV)
 - additional AA & pA combinations



ALICE Timeline

(before latest developments, to be revised)

- **2010-2012:** complete the approved detector configuration by adding modules of PHOS, **TRD** and **EMCal** (plus the 6-module *extension* **Dca**l). During the same period, upgrade R&D effort will continue to progress for VHMPID, for innovative pixel detectors, TPC readout, DAQ and for high-density calorimetry for FOCAL.
 - Critical for any design definition are the first Heavy Ion data to be taken in November 2010
 - During the 2012 shutdown, installation of VHMPID Module-0 in ALICE to asses the technology (part of R&D)
- 2013-2014: Decisions on upgrade plans in terms of physics strategy, based on analysis of the first data, detector feasibility, results of the R&D, funding availability, and approval by LHCC.



"old" timeline continued

- 2015 shutdown install a Phase I upgrade. For ALICE, it could include TPC readout, DAQ, VHMPID and Phase-I FOCAL (in the PMD location).
- 2017 : Install major upgrades requiring the change of the beampipe, could include (some elements like Phase-II FoCal could be installed later):
 - ITS (addition of a small R layer + replacement of n of the existing layers)
 - Phase-II FoCal (very forward)
 - Forward tracking
 - Trigger and DAQ Upgrades
 - > NEEDS at least 12 months
- Priority for ALICE: fewer but longer shutdowns



Major Constraint: Installation of a new beampipe and new ITS detector

From past experience we can get a good estimate of the needed time:

Opening the experiment and moving the TPC to parking position	11 weeks
Disconnecting and removing ITS and beampipe	6 weeks
Moving ITS to the surface and perform modifications	x weeks
Reinstallation of new beampipe, ITS detector, commissioning	16 weeks
TPC to IP and closing the experiment	15 weeks
	=======
Total time without contingency->	48 +x weeks

Whether we just replace the Silicon Pixel Detector (x=0 weeks) or whether we also modify the Silicon Drift Detector or Silicon Strip Detector is still not decided. This would add at least (x=10 weeks).

 \rightarrow For the ALICE beampipe and tracker upgrade we need an absolute minimum of 1 year.



DCAL: Di-Jet Calorimeter

A 60% expansion of EMCal acceptance arranged to permit back-to-back hadron-jet and jet-jet correlations



Incorporate PHOS and new Pb/ Scint super modules to produce a single, large electromagnetic calorimeter patch back-to-back with EMCal

Acceptance $\Delta \eta x \Delta \phi = 1.4 \times 0.7$

PHOS modules

integration of VHMPID **~** modules

New DCal super modules



DCal+PHOS+VHMPID, Sideview





Common DCal / PHOS Insertion Tooling



PHOS Operation



Dcal Project organization (EMCAL + China and Japan)

China:

- Provide 1 DCal super module
- Proportional contribution of support structure costs
- Provide manpower for WLS fiber production for 3 SM in Frascati
- Proportional contribution of infrastructure, installation and integration costs
- Proportional contribution of electronics and trigger cost
- Proportional contribution to HLT and DAQ integration cost
- Provide proportional contribution to all shipping costs
- Proportional contribution of cosmic calibration manpower

France:

- Provide 0.5 DCal super modules (Nantes)
- Assemble and test all 2.5 EU and Asian strip modules (Nantes)
- Assemble and cosmic calibrate all DCal SMs: US, EU and Asian. (Grenoble)
- Provide engineering, design and fabrication oversight of support structure and installation tooling (Nantes)
- Proportional contribution of support structure costs
- Provide an advance of 200k euros toward the support structure cost in 2010
- DCal Installation oversight (Nantes)
- Proportional contribution of infrastructure, installation and integration costs
- Proportional contribution to HLT and DAQ integration cost
- Proportional contribution of electronics and trigger cost
- Provide proportional contribution to all shipping costs
- Proportional contribution of cosmic calibration manpower

Italy:

- Provide facilities, expertise and manpower for WLS fiber bundle assembly for EU and Asian modules (Frascati)
- provide module assembly tooling to Wuhan (two stations) (Frascati)
- provide module assembly tooling to Tsukuba (one station) (Catania & Frascati)
- Provide module assembly facilities, expertise and manpower for modules and strip modules for 0.5 Japanese SM (Catania)
- Provide facilities, expertise and manpower for all EU and Asian APD assembly and calibration (Catania)
- Contribution to US group of 2 DCal crates (Catania)
- Contribution of cosmic calibration manpower

Japan:

- Provide 1.5 DCal super modules (1 SM assembled in Japan, and for 0.5 in Catania)
- Provide manpower for APD assembly and calibration for 3 SM
- Proportional contribution of support structure costs
- Proportional contribution of infrastructure, installation and integration costs
- Proportional contribution of electronics and trigger cost
- Proportional contribution to HLT and DAQ integration cost
- Provide proportional contribution to all shipping costs
- Proportional contribution of cosmic calibration manpower

USA:

- ALICE DCal Project Management
- ALICE DCal Project Technical Coordination
- Provide module assembly tooling to Tsukuba (one station)
- Provide LED calibration fibers for the full DCal
- Provide APD plastic parts, fiber plastic parts
- Provide oversight of electronics procurement, installation and testing
- Provide 3 DCal super modules
- Proportional contribution of support structure costs
- Proportional contribution of infrastructure, installation and integration costs
- Proportional contribution of electronics and trigger cost
- Proportional contribution to HLT and DAQ integration cost
- Provide proportional contribution to all shipping costs
- Proportional contribution of cosmic calibration manpower (From all US Labs)



DCAL cost and schedule

Completion February 2011

DCAL System	Estimated Cost (kCH) 6 Supermodules
Mechanical Components production	1,744
Electronics Production	1,047
DCal Service Integration	174
Rails and Support Structure	436
Insertion Tooling	140
Total Shipping Cost	419
DCal total cost	3,959

	I dok Name	r man	Jun Juli u e Octi o e Janie MarApria Jun Juli u e Octi o e Jani
1	DCal Supermodule No. 1 Ready for Installation	Fri 2/18/11	
2	DCal Integration Into Alice	Fri 2/18/11	
3	Support Rails Design	Fri 4/30/10	
1	Support Cradle Design	Fri 4/30/10	
5	Insertion Tooling Preliminary Design	Fri 4/30/10	
5	Dcal Utilities/Services Integration Preliminary Design	Fri 4/30/10	
7	Design Review	Tue 5/25/10	45 ⁷²⁵
3	Rails Material Procurement	Mon 9/13/10	
9	Rail Fabrication	Mon 12/6/10	
0	Rails Available for Installation	Mon 12/6/10	↓ 2/6
1	Support Cradle Farication	Mon 1/3/11	
2	Support Cradle Ready for Installation	Mon 1/3/11	1 1/
3	Insertion Tooling Final Design	Fri 9/17/10	
4	Insertion Tooling Fabrication	Fri 1/7/11	
5	Utilities/Services Integration Final Design	Fri 8/20/10	
6	Utilities/Services Fabrication	Fri 11/12/10	
7	Services Ready for Installation	Fri 11/12/10	◆ 1142
8	DCal Integration Is Ready	Mon 1/3/11	\$11
9	DCal Supemodule Production	Fri 2/18/11	
0	Material Procurement	Fri 7/23/10	
1	Module Assembly in Japan	Fri 11/12/10	
2	Module Assembly in China	Fri 1/7/11	││ │ │ │ ││ <mark>┶┿╼╼</mark> ─
3	Module Assembly in France	Fri 10/15/10	
4	StripModule Assembly In Nantes	Fri 2/4/11	
5	Module and Stripmodule production at WSU	Fri 1/7/11	
6	Dcal SM No. 1 Assembly at Grenoble (USA)	Fri 10/15/10	
7	DCal Supermodule No. 1 Ready for Installation	Fri 10/15/10	▲ 10/15
8	Dcal SM No. 2 Assembly at Grenoble (Japan)	Fri 12/10/10	
9	DCal Supermodule No. 2 Ready for Installation	Fri 12/10/10	▲ 12/10
0	Dcal SM No. 3 Assembly at Grenoble (USA)	Fri 12/10/10	
1	DCal Supermodule No. 3 Ready for Installation	Fri 12/10/10	▲ 12/10
2	Dcal SM No. 4 Assembly at Grenoble (Japan-Fran	Fri 1/28/11	
3	DCal Supermodule No. 4 Ready for Installation	Fri 1/28/11	
4	Dcal SM No. 5 Assembly at Grenoble (USA)	Fri 2/4/11	
5	DCal Supermodule No. 5 Ready for Installation	Fri 2/4/11	
6	Dcal SM No. 6 Assembly at Grenoble (China)	Fri 2/18/11	
7	DCal Supermodule No. 6 Ready for Installation	Fri 2/18/11	
8	Dcal Supermodule Production Is complete	Fri 2/18/11	

Quick status of other projects

- Studies to define the projects progress
- R&D programs have been launched and are vigorously pursued:
 - Fast drift and fast readout for TPC
 - Enhanced capacity DAQ
 - Hadron Identification up to over 20 GeV
 - High density Calorimetry
 - Low-mass, high-resolution pixel detectors

• Comprehensive report last time, concentrate on few items now



FoCal Physics Motivation

- Study low-x parton distributions
 - implies large rapidities

$$x \approx \frac{p_T}{\sqrt{s}} \exp(-y) \approx \frac{p_T}{\sqrt{s}} \exp(-\eta)$$

- Main physics issues:
 - gluon saturation (pA)
 - elliptic flow (AA)
 - rapidity gap reduces non-flow
 - long-range rapidity correlations: ridge (AA)

- Provide forward (η > 3)
 coverage for identified particle
 measurements
 - EM calorimeter for photons, neutral pions (eta?), jets
 - Requires high granularity (lateral and longitudinal)
- Favoured technology: SiW
- Phased approach
 - Phase 1: inside magnet, η < 4.5
 - Phase 2: outside magnet, $\eta > 4.5$



Signals of gluon saturation

- At forward forward rapidities:
 - Single hadron suppression
 - De-correlation of recoil yield
- Interesting observations at RHIC, consistent with gluon saturation
 - Still too low p_T! Reference measurement not describable by pQCD?
 - Limited by small saturation scale
- Measurements at LHC advantageous
 - Larger kinematic reach (smaller x)!
 - Larger saturation scale: larger p_T possible!



optimum position for phase 1 FoCal: - Inside magnet at maximum distance (before T0, flange, etc.) options: later addition of phase 2 detector further downstream (larger rapidities)? detector integrated in muon absorber?

Institutes/Current Activities

- Tokyo (simulation, electronics R&D, prototype tests, 10x10 mm² pads)
- Kolkata + collaborating Indian institutes (simulation, Si-strips)
- Utrecht/Nikhef (simulation)
- Yonsei (prototype tests)
- Prague, Jyväskylä
- expression of interest: Bergen, Copenhagen, Nantes, Oak Ridge, ...



Design Decisions

- technology: Si-W sandwich
 - active layers pads and/or strips
- location: 3.5 m from vertex (replacing PMD)
 - alternative option to be studied: integrate in muon absorber
- pad size: 10 x 10 mm² or smaller
- tower geometry

- bring services to back of detector



Open Design Issues

- exact granularity?
 - Driven by overlap probability in heavy ion collisions
 - Needs November data on Multiplicity
 - information on longitudinal shower development
- dynamic range?
 - depends on granularity
 - consequences for front-end electronics
- electronics/integration
 - front-end electronics: only preamp/shaper or also ADC, integrated in Si layers?
 - modify existing design?





2010	crucial design decisions: granularity, dynamic range, eta coverage establish options for front end electronics prepare Letter of Intent
2011	detailed simulations and mechanics design: number of layers, exact thickness, necessary gaps, etc. electronics R&D, construction of physics prototype
2012	physics prototype in beam (test beam or physics beam?) continue electronics R&D
2013	production, tests
2014	production, tests
2015	detector installation



	max	min						
radius [cm]	75	75						
layers	30	21						
pad size [cm ²]	0.5x0.5	1x1						
# of channels 2 120 000		371 000						
mechanics, cooling etc.	2 000 k€	2 000 k€						
tungsten	380 k€	270 k€						
Si sensors	5 300 k€	3 700 k€						
read-out	5 300 k€	930 k€						
total	12 980 k€	6 900 k€						

Extending ALICE PID capability: The VHMPID project

- RHIC results: importance of high momentum particles as hard probes and the need for particle identification in a very large momentum range, in particular protons.
- The VHMPID (Very High Momentum PID) detector will extend the track-by-track identification capabilities of ALICE up to ~ 26 GeV/c
- The VHMPID will also represent a tool to help TPC in calibration of PID based on dE/dx





- It is a RICH in focusing geometry using 80 cm C₄F₁₀ gaseous radiator, segmented spherical mirror and CsI-based photodetector (with MWPC or Thick-GEM)
- Same HMPID FEE, based on Gassiplex chip
- Most of the design derived from HMPID know-how, issues needing R&D:
 - CsI-TGEM reliability over large area
 - Pad cathode segmentation and structure
 - Large area quartz windows segmentation and fixation
 - Spherical mirror structure and segmentation

The VHMPID collaboration

E. Cuautle, I. Dominguez, D. Mayani, A. Ortiz, G. Paic, V. Peskov R. Alfaro M. Martinez, S. Vergara, A. Vargas G. De Cataldo, D. Di Bari, E. Nappi, C. Pastore, I. Sgura, G. Volpe A. Di Mauro, P. Martinengo, L.Molnar, D. Perini, F. Piuz, J. Van Beelen A. Agocs, G.G. Barnafoldi, G. Bencze, L. Boldizsar, E. Denes, Z. Fodor, E. Futo, G. Hamar, P. Levai, C. Lipusz, S. Pochybova D. Varga E. Garcia J. Harris, N. Smirnov In-Kwon Yoo, Changwook Son, Jungyu Yi

Integration in ALICE

- Design constraint: exploit all available space to maximize acceptance
- Tilted single modules: problems with different clearance in S10 and S11, acceptance ~ 8% wrt to TPC in $|\eta| < 0.5$ (jet fully contained)
- <u>"Super-modules" layout</u>: h=130 cm everywhere, acceptance ~ 12%
- Module-0 size doubled acceptance (~ 3%) due to new PHOS support structure (i.e. no cradle in S11)



new layout, super-modules



Supermodule layout



Module-O layout



Cooling+cover: 3cm Trigger A + MIP layer: 16cm Photon-detector+FEE: 8cm

 C_4F_{10} radiator: 80 cm

Mirror+cover: 4cm

Trigger B + MIP layer: 16cm

Cooling+cover: 3cm

Total: 130 cm

Beam tests program

Period A	1-19 Jul	PS/T10	TGEM
Period B	16-30 Aug	PS/T10	HPTD
Period C	27 Sept-11 Oct	PS/T10	Small prototype
Period D	1-8 Nov	SPS/H4	HPTD+Small
			prototype

Module-O production planning

ID	Task Name	2010				2010 2011								2012										
		Jan	Mar	May	Jul	Sep	Nov	Jan	Mar	May	Jul	Sep	Nov	Jan	Mar	May	Jul	Sep	Nov	Jan	Mar			
1	Detector layout simulation/engineering studies				1																			
2	Mirror segmentation			i	i																			
3	Cathode plane segmentation		ı 1	1	1																			
4	Pad size		:	:)																		
5	Window fixation, u-strip coating		:	!																				
6	FEE								\supset															
7	cooling panel																							
8	Procurement/production (small prototype, 2010			-																				
9	Mirror and support																							
10	Windows			C																				
11	Radiator vessel			C	;	>																		
12	Radiator gas system (temporary)																							
13	testbeam (PS and SPS))																	
14	HPTD (20x20 prototype, new FEE, L0/L1 FPGA)																							
15	lab tests		:	:	D																			
16	beam test																							
17	TGEM (1xTGEM + 6xTGEM area prototypes)	_			-																			
18	lab tests (layout, HV setting, FEE optimization)		; ,	i '	•																			
19	beam tests			1	0																			
20	Procurement/production (small prototype, 2011						5	_		_														
21	New FEE				1																			
22	New pad cathode (segmentation/pad size)																							
23	Full scale prototype (Module-0)											:	-											
24	Construction drawings								i															
25	Procurement											, ,	•											
26	Assembly											• !	• · ·				Ð							
27	Commissioning in lab																Č	Ð						
28	Testbeam SPS																	Č	Ð					
29	Installation in ALICE																		Č)				



- Present 6 detector layers based on three silicon technologies:
 - SPD (pixels)
 - SDD (Si Drift)
 - SSD (Si strips)
- Unique levelzero trigger (fast OR)

Radii: 4, 7, 15, 24, 39, and 44 cm Total material budget of $7\%X_0$ (normal incidence) Pixel size 50 µm times 425 µm Beam pipe radius 2.98 cm

Inner Tracking System upgrade

- Goal: a factor of 2 improvement in impact parameter resolution
- Secondary goal: improve stand-alone tracking capability
- Improving the impact parameter resolution by a factor 2 or better will:
 - Increase sensitivity to charm by factor 100;
 - Give access to charmed baryons (baryon/meson ratio in charm sector main issue is understanding of recombination);
 - Allow study of exclusive B decays;
 - Allows first measurement of total B production cross section down to zero P_{T} ;
 - Improve flavor tagging.

Inner Tracking System Upgrade

> Detector Layout and Technology:

- 6/7 cylindrical layers
- First layer as close as possible to the interaction point: smaller and thinner beam-

pipe (present 29/0.8mm)

goal: at least O(20mm) radius or smaller

- Extend the use of pixel detectors to larger radii (replace SDD, slowest det in ITS)
 - strips where pixels not affordable
 - re-use of the existing pixel and/or strip layers being considered
- Extremely low material budget, trigger capability, granularity, fast readout
- New mechanics and cooling

Target dates defined by the LHC shutdown schedule: 2017





ITS Upgrade Time-scale

> R&D phase: 2010-2013/14

- Explore two Pixel technologies:
 - Hybrid pixel detectors: "state of the art"
 - low cost bump-bonding
 - new sensor type (3D, edgeless planar)
 - further thinning (SPD: 200 μ m sensor + 150 μ m FEE)
 - Monolithic pixel detectors: Mimosa and LePix
 - larger detector areas at considerably lower cost
- Layout Studies and Technical Design report
- Production and pre-commissioning: 2014-2016
- > Installation and commissioning: 2017



R&D Progress

• Hybrid Pixels:

- Investigating possible application of hybrid silicon pixel detectors by studying possibilities to reduce the material budget
- 3 main targets defined
 - Thinning studies of chip wafers (150 μm in ALICE SPD, is 50-100 μm feasible?)
 - Thin silicon sensors (reduce the thickness from 200 um to 150 um, non-linear yield problem!)
 - Reduce the need for overlaps between modules (active edge, 3D sensor technologies)

• Lepix:

- Submission in 90nm finalized March 2010, prototypes expected back now
 - Several issues: ESD, special layers and mask generation, guard rings
- 7 chips submitted :
 - 4 test matrices
 C90_MATRIX1_V0...C90_MATRIX4_V0
 - 1 diode for radiation tolerance C90_DIODE_V0
 - 1 breakdown test structure C90_VBRDOWN_V0
 - 1 transistor test: already submitted once in test submission C90_TESTC90_V1
- Very significant testing effort for which we need to prepare (measurement setup, test cards...)



Happening ... 3D assemblies

FBK 3D sensor wafer

Details of the SPD-ALICE-3D sensor





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5 single chip assembly: SPD-ALICE-3D + ALICE1LHCb





3D prototype

Single chip assembly glued and wirebonded to the test card







